

Rev 1.0 08/01/19

General purpose medium power amplifier or switch in bare die form Complement to PNP BC556

Features:

- Gain graded
- Low saturation voltage
- Well suited for amplifier applications
- High reliability gold back metal
- High reliability tested grades for Military + Space

Ordering Information:

The following part suffixes apply:

- No suffix MIL-STD-750 /2072 Visual Inspection
- "H" MIL-STD-750 /2072 Visual Inspection+ MIL-STD-38534 Class H LAT
- "K" MIL-STD-750 /2072 Visual Inspection+ MIL-STD-38534 Class K LAT

LAT = Lot Acceptance Test.

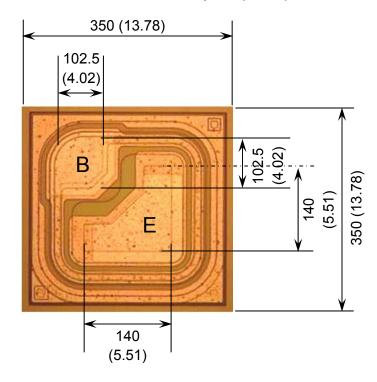
For further information on LAT process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape Specific request
- Unsawn Wafer Specific request
- With additional electrical selection Specific request
- Sawn as pairs or adjacent pair pick Specific request

Die Dimensions in µm (mils)



E = EMITTER **B** = BASE

DIE BACK = COLLECTOR

Mechanical Specification

Die Size (Excluding Saw Street)	350 x 350 13.78 x 13.78	µm mils	
Base Pad Size	102.5 x 102.5 4.02 x 4.02	μm	
Emitter Pad Size	96 x 96 5.51 x 5.51	mils	
Die Thickness	230 (±15) 9.06 (±0.59)	μm mils	
Top Metal Composition	Al - 1.3μm		
Back Metal Composition	AuAs - 0.9μm		





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Absolute Maximum Ratings T_A = 25°C unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Collector-Base Voltage	V _{CBO}	80	V
Collector-Emitter Voltage	V _{CEO}	65	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current	Ic	100	mA
Junction Temperature	TJ	150	°C
Storage Temperature	T _{stg}	-55 to 150	°C

Electrical Characteristics T_A = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Collector-Base Breakdown Voltage	V _{(BR)CBO}	$I_{\rm C} = 50 \mu A, I_{\rm E} = 0$		50	-	-	V
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	I _C = 1mA, I _B = 0		45	-	-	V
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	$I_E = 50 \mu A, I_C = 0$		6	-	-	V
Collector Cut-off Current	I _{CBO}	V _{CB} = 30V, I _E = 0		-	-	15	nA
ON CHARACTERISTICS							
Forward-Current Transfer Ratio ¹	h _{FE}	BC546	V _{CE} = 5V, I _C = 2mA	110	-	800	-
		BC546A		110	-	220	-
		BC546B		200	290	450	-
		BC546C		420	-	800	-
		BC546A	$V_{CE} = 5V, I_{C} = 10\mu A$	-	90	-	-
			$V_{CE} = 5V, I_{C} = 100mA$	-	120	-	-
		BC546B	$V_{CE} = 5V, I_{C} = 10\mu A$	-	150	-	-
			$V_{CE} = 5V, I_{C} = 100mA$	-	180	-	-
Collector-Emitter Saturation Voltage	V _{CE(sat)}	$I_C = 10 \text{mA}, I_B = 0.5 \text{mA}$		-	90	250	mV
		$I_C = 100$ mA, $I_B = 5$ mA		-	200	600	mV
Base-Emitter Saturation Voltage	V _{BE(sat)}	I _C = 10mA, I _B = 0.5mA		-	700	-	mV
		I _C = 100mA, I _B = 5mA		-	900	-	mV
Base-Emitter On Voltage	V _{BE(on)}	$I_C = 2mA$, $V_{CE} = 5V$		580	660	700	mV
		$I_C = 10$ mA, $V_{CE} = 5$ V		-	-	720	mV
SMALL SIGNAL CHARACTERISTICS							
Transition Frequency ³	f _T	V _{CE} = 5V, I _C = 10mA, f = 100MHz		150	300	-	MHz
Small-Signal Current Gain	h _{fe}	BC546)/ 5)/ I O A	125	-	900	
		V_{CE} = 5V, I_{C} = 2mA, f = 1 kHz		125	220	260	
		BC546B		240	330	500	
Output Capacitance	C _{obo}	V _{CB} = 10V, I _E = 0, f = 1MHz		-	3.5	6	pF
Input Capacitance	C _{ibo}	V _{BE} = 10V, I _C = 0, f = 1MHz		-	9	-	pF
Noise Figure	NF	V_{CE} = 5V, I_C = 200μA, f = 1KHz, R_G =2K Ω		-	2	10	dB

Note 1: Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2%

Note 2: Not production testing in die form. Characterized by chip design and tested in package

Note 3: f_T is defined as the frequency at which $\mid h_{fe} \mid$ extrapolates to unity.





Typical Characteristics T_A = 25°C unless otherwise stated

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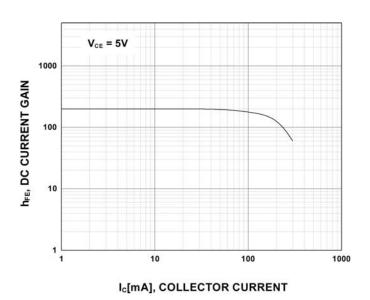


Figure 1 - DC Current Gain

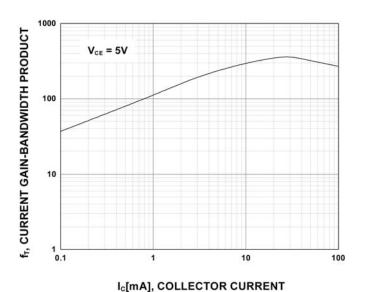


Figure 3 – Current Gain Bandwidth Product

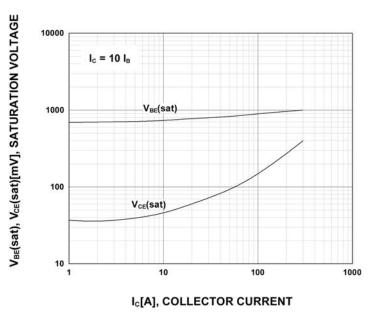


Figure 3 – Base-Emitter Saturation Voltage versus Collector-Emitter Saturation Voltage

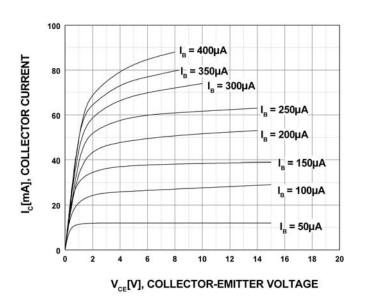
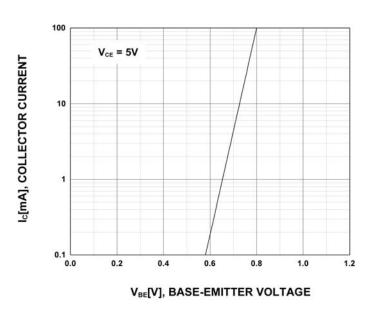


Figure 4 – Static Characteristics





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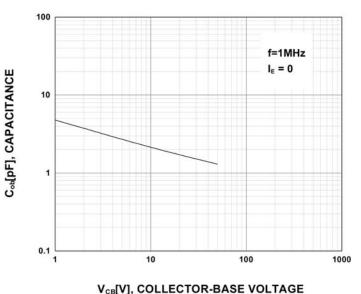


Figure 5 – Transfer Characteristic

Figure 6 – Output Capacitance

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